

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	43	electrostatic adj chuck same ceramic same bonding	US-PGPUB; USPAT	OR	ON	2003/05/22 11:35
S2	4	electrostatic adj chuck same ceramic same bonding same polyimide	US-PGPUB; USPAT	OR	ON	2003/05/22 11:36
S3	5	electrostatic adj chuck same ceramic same (bond bonding) same polyimide	US-PGPUB; USPAT	OR	ON	2003/05/22 11:37
S4	9	electrostatic adj chuck same ceramic same (bond bonding adhesive) same polyimide	US-PGPUB; USPAT	OR	ON	2003/05/22 16:07
S5	16	electrostatic adj chuck same ceramic same (silicone acrylic) same polyimide	US-PGPUB; USPAT	OR	ON	2003/05/22 14:37
S6	1	electrostatic adj chuck same bond same ceramic same (silicone acrylic) same polyimide	US-PGPUB; USPAT	OR	ON	2003/05/22 14:38
S7	3	electrostatic adj chuck and bond same ceramic same (silicone acrylic) same polyimide	US-PGPUB; USPAT	OR	ON	2003/05/22 14:47
S8	12	("4252394" "4565601" "4645218" "4655218" "4724510" "4838978" "4846929" "5275683" "5348497" "5486975" "5515167" "5528451").PN.	USPAT	OR	ON	2003/05/22 14:41
S9	17	("4565601" "4645218" "4724510" "4838978" "4846929" "4897171" "5221403" "5250137" "5255153" "5270266" "5275683" "5310453" "5314573" "5348497" "5486975" "5515167" "5528451").PN.	USPAT	OR	ON	2003/05/22 15:13
S10	4	electrostatic adj chuck and (bond bonding bonded adhesive) same ceramic same (silicone acrylic) same polyimide	US-PGPUB; USPAT	OR	ON	2003/05/22 14:48
S11	4	"6,071,630"	USPAT	OR	ON	2003/05/22 15:44
S12	20	"5,691,876"	USPAT	OR	ON	2003/05/22 15:44
S13	17	("4565601" "4645218" "4724510" "4838978" "4846929" "4897171" "5221403" "5250137" "5255153" "5270266" "5275683" "5310453" "5314573" "5348497" "5486975" "5515167" "5528451").PN.	USPAT	OR	ON	2003/05/22 15:44

S14	17	("4565601" "4645218" "4724510" "4838978" "4846929" "4897171" "5221403" "5250137" "5255153" "5270266" "5275683" "5310453" "5314573" "5348497" "5486975" "5515167" "5528451").PN.	USPAT	OR	ON	2003/05/22 15:45
S15	18	"5691876".URPN.	USPAT	OR	ON	2003/05/22 15:49
S16	0	electrostatic adj chuck same ceramic same roghness	US-PGPUB; USPAT	OR	ON	2003/05/22 16:08
S17	0	electrostatic adj chuck same ceramic and roghness	US-PGPUB; USPAT	OR	ON	2003/05/22 16:10
S18	157	electrostatic adj chuck same ceramic and grooves	US-PGPUB; USPAT	OR	ON	2003/05/22 16:10
S19	394876	electrostatic adj chuck same ceramic same grooves same depth	US-PGPUB; USPAT	OR	ON	2003/05/22 16:11
S20	0	electrostatic adj chuck same ceramic same grooves same depth	US-PGPUB; USPAT	OR	ON	2003/05/22 16:11
S21	0	electrostatic adj chuck same ceramic same grooves same depth	US-PGPUB; USPAT	OR	ON	2003/05/22 16:11
S22	20	electrostatic adj chuck same ceramic same grooves	US-PGPUB; USPAT	OR	ON	2003/05/22 16:26
S23	13	("3571678" "3916270" "4257083" "4426654" "4554611" "4645218" "4665463" "4751609" "4803595" "4897171" "4975802" "5047892" "5055964").PN.	USPAT	OR	ON	2003/05/22 16:25
S24	5	"6,28,762"	US-PGPUB; USPAT	OR	ON	2003/05/22 16:26
S25	5	"6,028,762"	US-PGPUB; USPAT	OR	ON	2003/05/22 16:36
S26	11	("5160152" "5413360" "5426558" "5452177" "5522131" "5530616" "5535090" "5548470" "5583736" "5631803" "5761023").PN.	USPAT	OR	ON	2003/05/22 16:31
S27	811	361/234	US-PGPUB; USPAT	OR	ON	2003/05/22 16:36
S28	193	361/234 and polyimide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 09:08
S29	49	361/234 and polyimide and ceramic and (silicone acrylic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 15:12

S30	39	361/234 and polyimide and ceramic and (silicone acrylic) and (bond bonding adhesive adherent)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 11:22
S31	23	"5,631,803"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 11:23
S32	14	("2443987" "3627338" "4184188" "4357006" "4384918" "4399016" "4771730" "5103367" "5275683" "5363098" "5452177" "5484485" "5486975" "5530616").PN.	USPAT	OR	ON	2003/05/23 11:14
S33	14	("2443987" "3627338" "4184188" "4357006" "4384918" "4399016" "4771730" "5103367" "5275683" "5363098" "5452177" "5484485" "5486975" "5530616").PN.	USPAT	OR	ON	2003/05/23 11:15
S34	69	"4,665,463"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 11:20
S35	138	"4,184,188"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 11:20
S36	6	("4184188" "4384918" "4399016" "4771730" "5275683" "5530616").PN.	USPAT	OR	ON	2003/05/23 11:22
S37	10	"5,631,803" and (bond bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 13:42
S38	3	"6,256,187"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 13:42
S39	0	361/234 and ceramic same aluminum adj nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 15:14

S40	0	361/234 and aluminum adj nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 15:14
S41	212	361/234 and aluminum adj nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 15:15
S42	133	361/234 and aluminum adj nitride same electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 15:15
S43	28	361/234 and aluminum adj nitride same electrode same sintering	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 15:49
S44	3	361/234 and aluminum adj nitride same electrode same flatness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 15:49
S45	573	279/128	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/23 16:33
S46	607	361/233	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/26 10:14
S47	1	electrostatic adj chuck and vacuum adj (pack packing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/26 11:30
S48	4	electrostatic adj chuck and vacuum same (pack packing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/26 11:49
S49	2	("3026210" "4285732").PN.	USPAT	OR	ON	2003/05/26 11:40
S50	462	electrostatic adj chuck and vacuum same heat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/26 11:50

S51	8	electrostatic adj chuck and vacuum same heat same (sinter sintering)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/26 11:50
S52	8	electrostatic adj chuck and silicone adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/30 11:08
S53	6	("4184188" "4502094" "4520421" "4864461" "4999507" "5055964").PN.	USPAT	OR	ON	2003/10/30 11:06
S54	141	"4,184,188"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/30 11:08
S55	1	"4,184,188" and silicone adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/30 11:08
S56	38	"4,184,188" and silicone	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/30 11:08
S57	135	"4,184,188"	US-PGPUB; USPAT	OR	ON	2003/11/14 15:02
S58	19	"1,443,215"	US-PGPUB; USPAT	OR	ON	2003/11/14 15:00
S59	191197	"4,184,188" and silicone	US-PGPUB; USPAT	OR	ON	2003/11/14 15:02
S60	37	"4,184,188" and silicone	US-PGPUB; USPAT	OR	ON	2003/11/14 15:23
S61	0	"4,184,188" and silicone adj(bond bonding)	US-PGPUB; USPAT	OR	ON	2003/11/14 15:23
S62	0	electrostatic adj chuck and silicone adj(bond bonding)	US-PGPUB; USPAT	OR	ON	2003/11/14 15:23
S63	0	electrostatic adj chuck and silicone adj2 (bond bonding)	US-PGPUB; USPAT	OR	ON	2003/11/14 15:24
S64	175	electrostatic adj chuck and silicone	US-PGPUB; USPAT	OR	ON	2003/11/14 15:24
S65	0	electrostatic adj chuck and silicone adj2 (bond bonding)	US-PGPUB; USPAT	OR	ON	2003/11/14 15:24
S66	15	electrostatic adj chuck and silicone same (bond bonding)	US-PGPUB; USPAT	OR	ON	2003/11/14 15:43

S67	7	electrostatic adj chuck and silicone adj layer	US-PGPUB; USPAT	OR	ON	2003/11/14 15:43
S68	12	electrostatic adj chuck and silicone adj2 layer	US-PGPUB; USPAT	OR	ON	2003/11/14 16:22
S69	11	("4340462" "4579618" "4615755" "4665463" "4692836" "4948458" "5013400" "5055964" "5200232" "5262029" "5326725").PN.	USPAT	OR	ON	2003/11/14 16:10
S70	8	"5798904".URPN.	USPAT	OR	ON	2003/11/14 16:13
S71	43	silicone adj2 layer adj adhesive	US-PGPUB; USPAT	OR	ON	2003/11/14 16:22
S72	6	"6,071,630"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/16 11:30
S73	891	361/234	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/17 09:38
S74	10	("5103367" "5708250" "5737175" "5812361" "5835333" "5835335" "5894400" "6125025" "6273023" "6361645").PN.	USPAT	OR	ON	2003/11/17 09:38
S75	21	("4565601" "5213349" "5230741" "5310453" "5320982" "5443689" "5474614" "5516367" "5522131" "5531835" "5583736" "5656093" "5792304" "5906684" "5961774" "5985035" "6048434" "6217705" "6221201" "6336991" "6524428" "2001/0009178" "2001/0025608" "2002/0046706" "2002/0096116" "2002/0104618" "2002/0108574").PN.	USPAT	OR	ON	2003/11/17 09:39
S76	599	279/128	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/17 10:53

S77	34	("4340462" "4534816" "4579618" "4615755" "4665463" "4692836" "4948462" "5055964" "5155652" "5160152" "5200232" "5221403" "5238499" "5262029" "5280156" "5350479" "5511799" "5663865" "5671117" "5730803" "5796066" "5800618" "5820723" "5835334" "5851298" "5867359" "5880922" "5883778" "5908334" "5922133" "5930639" "5948704" "5968273" "6239402").PN.	USPAT	OR	ON	2003/11/17 10:53
S78	34	("4340462" "4534816" "4579618" "4615755" "4665463" "4692836" "4948462" "5055964" "5155652" "5160152" "5200232" "5221403" "5238499" "5262029" "5280156" "5350479" "5511799" "5663865" "5671117" "5730803" "5796066" "5800618" "5820723" "5835334" "5851298" "5867359" "5880922" "5883778" "5908334" "5922133" "5930639" "5948704" "5968273" "6239402").PN.	USPAT	OR	ON	2003/11/17 10:53
S79	34	("4340462" "4534816" "4579618" "4615755" "4665463" "4692836" "4948462" "5055964" "5155652" "5160152" "5200232" "5221403" "5238499" "5262029" "5280156" "5350479" "5511799" "5663865" "5671117" "5730803" "5796066" "5800618" "5820723" "5835334" "5851298" "5867359" "5880922" "5883778" "5908334" "5922133" "5930639" "5948704" "5968273" "6239402").PN.	USPAT	OR	ON	2003/11/17 10:53
S80	5	("5160152" "5530616" "5761023" "5880923" "6028762").PN.	USPAT	OR	ON	2003/11/17 10:54
S81	642	361/233	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/17 11:46

S82	4	"6,256,187"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/03/08 11:33
S83	6	"6,071,630"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/03/08 11:33
S84	7	"5,909,355"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/03/08 11:34
S85	31	"5,835,334"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/03/08 11:34
S86	19	"6,108,189"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/03/08 11:35
S87	974	361/234	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/02 15:17
S88	0	bonding adj layer near polyimide adj layer	US-PGPUB; USPAT	OR	ON	2004/12/22 13:40
S89	35	bonding adj layer same polyimide adj layer	US-PGPUB; USPAT	OR	ON	2004/12/22 13:46
S90	1	bonding adj layer same polyimide adj layer same double	US-PGPUB; USPAT	OR	ON	2004/12/22 13:46
S91	1	bonding adj layer same polyimide adj layer same (double dual)	US-PGPUB; USPAT	OR	ON	2004/12/22 13:47
S92	4	bonding adj layer same polyimide same (double dual)	US-PGPUB; USPAT	OR	ON	2004/12/22 14:04
S93	1	10/044,500	US-PGPUB; USPAT	OR	ON	2004/12/22 14:41
S94	5	"6,071,630"	US-PGPUB; USPAT	OR	ON	2004/12/22 14:41
S95	5	"6,256,187"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/04/04 11:26

S96	7	"6,071,630"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/04/04 12:29
S97	8	("4184188" "4931135" "5191506" "5382469" "5413360" "5645921" "5646814" "5753132").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:32
S98	3630	electrostatic adj chuck	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:32
S99	1778	electrostatic adj chuck and ceramic	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:32
S10 0	496	electrostatic adj chuck and ceramic and (bond bonding)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:33
S10 1	0	electrostatic adj chuck and ceramic and (bond bonding) near laer	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:33
S10 2	80	electrostatic adj chuck and ceramic and (bond bonding) near layer	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:40
S10 3	3	electrostatic adj chuck and ceramic and (bond bonding) near layer same polyimide	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:34
S10 4	1	electrostatic adj chuck and ceramic and (bond bonding) near layer same polyimide same (silicon acrylic)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:34
S10 5	5	electrostatic adj chuck and ceramic and (bond bonding) near layer and polyimide same (silicon acrylic)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:40
S10 6	344	ceramic and (bond bonding) near layer and polyimide same (silicon acrylic)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:42
S10 7	48	ceramic near metal and (bond bonding) near layer and polyimide same (silicon acrylic)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:59
S10 8	0	ceramic near metal near (bond bonding) and bonding near layer and polyimide same (silicon acrylic)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:48
S10 9	5	ceramic near metal near (bond bonding) and polyimide same (silicon acrylic)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:48

S11 0	18	("2067213" "3132044" "3323204" "3346946" "3434197" "3439408" "3473943" "3474520" "3543388" "R026858").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:49
S11 1	143	ceramic near metal and (bond bonding) near layer and polyimide	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 12:59
S11 2	9	electrostatic near chuck and ceramic near metal and (bond bonding) near layer and polyimide	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 13:24
S11 3	68	electrostatic near chuck and kapton	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 13:26
S11 4	0	electrostatic near chuck and kapton same two near (side sided)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 13:25
S11 5	0	electrostatic near chuck and kapton same (double two) near (side sided)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 13:25
S11 6	0	electrostatic near chuck and bonding near layer same kapton	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 13:26
S11 7	13	electrostatic near chuck and bonding near layer and kapton	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 13:41
S11 8	0	electrostatic near chuck and bonding near layer and kapton near fn	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 13:35
S11 9	1	bonding near layer and kapton near fn	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 13:35
S12 0	0	electrostatic near chuck and bonding near layer same kapton	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 13:41
S12 1	6	electrostatic near chuck and (bonding bond) same kapton	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 13:51
S12 2	896	(bonding bond) same kapton	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 13:51
S12 3	0	(bonding bond) near dual near side same kapton	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 15:07
S12 4	3651	electrostatic near chuck	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 15:08

S12 5	211	electrostatic near chuck and electrode near embedded	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 15:08
S12 6	19	electrostatic near chuck and electrode near embedded near ceramic	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 15:58
S12 7	2	electrostatic near chuck and electrode near embedded near ceramic and bonding near layer	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 15:16
S12 8	2	electrostatic near chuck and electrode near embedded near ceramic and (bond bonding) near layer	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 15:16
S12 9	7	"6,379,745"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/04 15:58
S13 0	7	"6,057,513"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 09:44
S13 1	112	electrostatic near chuck and metal near base	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 09:44
S13 2	29	electrostatic near chuck and metal near base and ceramic near chuck	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 11:50
S13 3	12	electrostatic near chuck and metal near base and ceramic near chuck and (bond bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 09:50
S13 4	0	electrostatic near chuck and metal near base and ceramic near chuck and (bond bonding) near polymer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 09:50
S13 5	2	electrostatic near chuck and metal near base and ceramic near chuck and (bond bonding) same polymer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 09:50
S13 6	366	electrostatic near chuck and polyimide	USPAT	OR	OFF	2005/04/05 09:59
S13 7	4	electrostatic near chuck and (bond bonding) near polyimide	USPAT	OR	OFF	2005/04/05 10:00

S13 8	4	electrostatic near chuck and (bond bonding) near polyimide and silicone	USPAT	OR	OFF	2005/04/05 10:26
S13 9	4	electrostatic near chuck and (bond bonding) near polyimide and silicon	USPAT	OR	OFF	2005/04/05 10:27
S14 0	4	(bond bonding) near polyimide near silicon	USPAT	OR	OFF	2005/04/05 10:29
S14 1	0	(bond bonding) near polyimide near (silicone acrylic)	USPAT	OR	OFF	2005/04/05 10:30
S14 2	4	(bond bonding) near polyimide near (silicon acrylic)	USPAT	OR	OFF	2005/04/05 10:30
S14 3	45	(bond bonding) near polyimide same (silicon acrylic)	USPAT	OR	OFF	2005/04/05 10:30
S14 4	6	(bond bonding) near film same polyimide near (silicon acrylic)	USPAT	OR	OFF	2005/04/05 10:31
S14 5	5	electrostatic near chuck and metal near base and ceramic near chuck and flatness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 11:51
S14 6	0	electrostatic near chuck and ceramic near chuck near flatness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 11:51
S14 7	7	electrostatic near chuck and ceramic near chuck same flatness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 11:55
S14 8	13	electrostatic near chuck and ceramic near chuck same (flatness roughness)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 12:10
S14 9	2	"2002261157"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 12:50
S15 0	1048	361/234	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 12:50